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REGULAR PAPERS

Advanced Packaging Technologies

Realization of a Novel Weaving Framework in Looms for Manufacturing of E-Textiles	A. Anbalagan, E. F. Sundarsingh, and V. S. Ramalingam	199
The Sintering Process and Vibration Characteristics for Leadless Package Structure of Pressure Sensors	G. Xie, Z. Jin, J. Tian, X. Tang, and J. Li	209
A Method of Defect Detection for Focal Hard Samples PCB Based on Extended FPN Model	C.-j. Li, Z. Qu, S.-y. Wang, K.-h. Bao, and S.-y. Wang	217
Recent Advances and Trends in Advanced Packaging	J. H. Lau	228
Study on the Performance of Insulating Substrate Based on Silver Sintering	W. Zhao and X. Li	253

Components: Characterization and Modeling

The Impact of Variation in Filling Ratios, Evacuation Pressure, and Heat Input on Thermal Performance of Pulsating Heat Pipe	E. D. Patel and S. Kumar	259
Transient Behavior and Maldistribution of Two-Phase Flow in Parallel Channels	T. Aka and S. Narayan	270
Estimation of Heat Generation in Semiconductors Centrally Mounted on Printed Circuit Boards	J. V. T. Silveira, Z. Li, K. Fushinobu, R. Yasui, and T. Shinoda	280
A Wettability-Mediated Microdroplet Under Electrowetting Effect for Hotspot Cooling	I. Ahmad, A. Ranjan, M. Pathak, and M. K. Khan	288
Thermal and Mechanical Characterization of 2.5-D and Fan-Out Chip on Substrate Chip-First and Chip-Last Packages	M.-K. Shih, W. Lai, T. Liao, K. Chen, D.-L. Chen, and C. P. Hung	297

Electrical Performance of Integrated Systems

Modeling and Analysis of Signal Integrity of Ball Grid Array Packages With Failed Ground Solder Balls	K. Song, J. Gao, G. T. Flowers, Z. Wang, W. Yi, and Z. Cheng	306
Weighted Distribution Constraint Based Prediction of Available Interval of Coaxial-to-Microstrip Flexible Interconnection	J. Tian, J. Liu, S. Xue, L. Zhang, C. Zhou, S. Liu, Y. Wang, G. Leng, Y. Zou, X. Hu, and C. Wang	316
Multiconductor Transmission Lines for Orbital Angular Momentum (OAM) Communication Links	M. Wulff, T. Hillebrecht, L. Wang, C. Yang, and C. Schuster	329

(Contents Continued on Page 198)

Electronics Manufacturing	
IC Solder Joints Inspection via an Optimized Statistical Modeling Method	W. Chen, N. Cai, Z. Wu, H. Wang, and J. Ma
.....	341
Iterative Machine Learning-Aided Framework Bridges Between Fatigue and Creep Damages in Solder Interconnections	V. Samavatian, M. Fotuhi-Firuzabad, M. Samavatian, P. Dehghanian, and F. Blaabjerg
.....	349
Physical Modeling of Monolithic Self-Rolled-Up Microtube Interdigital Capacitors	X. Luo, Z. Yang, M. Kraman, L. Sang, Y. Zhang, X. Li, and W. Huang
.....	359
Selection and Characterization of Photosensitive Polyimide for Fan-Out Wafer-Level Packaging	R. Gao, R. Ma, J. Li, M. Su, F. Hou, and L. Cao
.....	368
Development of 3-D Wafer Level Packaging for SAW Filters Using Thin Glass Capping Technology	Z. Chen, D. Yu, and F. Jiang
.....	375
Environment-Adaptable Printed-Circuit Board Positioning Using Deep Reinforcement Learning	C. Solorzano and D.-M. Tsai
.....	382
<hr/> LETTERS	
Wideband Low-Profile Dual-Polarized Antenna Based on a Gain-Enhanced EBG Reflector	H. Q. Xiong, C. J. Zhang, and M. S. Tong
.....	391